200 W Transient Voltage Suppressor SOD-123 Flat Lead Package

The SMF5.0AT1G Series is designed to protect voltage sensitive components from high voltage, high energy transients. Excellent clamping capability, high surge capability, low zener impedance and fast response time. Because of its small size, it is ideal for use in cellular phones, portable devices, business machines, power supplies and many other industrial/consumer applications.

Features

- Stand-off Voltage: 5 58 Volts
- Peak Power 200 Watts @ 1 ms (SMF5.0A SMF58A)
- Low Leakage
- Response Time is Typically < 1 ns
- ESD Rating of Class 3 (> 16 kV) per Human Body Model
- ESD Rating of Level 4 (8 kV Contact Discharge) per IEC61000-4-2
- EFT (Electrical Fast Transients) Rating of 40 A per IEC61000–4–4
- Low Profile Maximum Height of 1.0 mm
- Small Footprint Footprint Area of 8.45 mm²
- Supplied in 8 mm Tape and Reel 3,000 Units per Reel
- Cathode Indicated by Polarity Band
- Lead Orientation in Tape: Cathode Lead to Sprocket Holes
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant*

Mechanical Characteristics:

CASE: Void-free, transfer-molded, thermosetting plastic Epoxy Meets UL 94 V-0 LEAD FINISH: 100% Matte Sn (Tin) MOUNTING POSITION: Any QUALIFIED MAX REFLOW TEMPERATURE: 260°C Device Meets MSL 1 Requirements



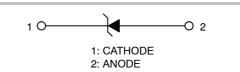
ON Semiconductor®

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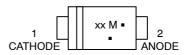
PLASTIC SURFACE MOUNT ZENER OVERVOLTAGE TRANSIENT SUPPRESSOR 5 – 58 VOLTS 200 WATT PEAK POWER



SOD-123FL CASE 498



MARKING DIAGRAM



xx = Device Code (Refer to page 3)

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
SMFxxxAT1G	SOD-123FL (Pb-Free)	3,000 / Tape & Reel
SZSMFxxxAT1G	SOD-123FL (Pb-Free)	3,000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

DEVICE MARKING INFORMATION See specific marking information in the device marking

column of the Electrical Characteristics table on page 3 of

this data sheet.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Maximum P_{pk} Dissipation (PW-10/1000 μ s) (Note 1) SMF5.0A – SMF58A	P _{pk}	200	W
Maximum P_{pk} Dissipation @ $T_A = 25^{\circ}C$, (PW-8/20 μ s) (Note 2)	P _{pk}	1000	W
DC Power Dissipation @ T _A = 25°C (Note 3) Derate above 25°C Thermal Resistance, Junction-to-Ambient (Note 3)	P _D R _{θJA}	385 4.0 325	mW mW/°C °C/W
Thermal Resistance, Junction-to-Lead (Note 3)	$R_{\theta Jcathode}$	26	°C/W
Operating and Storage Temperature Range	T _J , T _{stg}	–55 to +150	°C

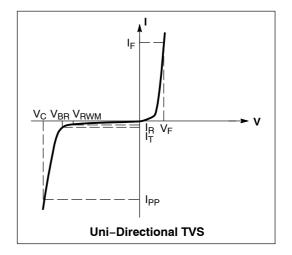
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Non-repetitive current pulse at $T_A = 25^{\circ}C$, per waveform of Figure 2. 2. Non-repetitive current pulse at $T_A = 25^{\circ}C$, per waveform of Figure 3. 3. Mounted with recommended minimum pad size, DC board FR-4.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted, $V_F = 3.5 V Max$. @ IF (Note 4) = 12 A)

Symbol	Parameter					
I _{PP}	Maximum Reverse Peak Pulse Current					
V _C	V _C Clamping Voltage @ I _{PP}					
V _{RWM} Working Peak Reverse Voltage						
I _R	Maximum Reverse Leakage Current @ V _{RWM}					
V_{BR}	Breakdown Voltage @ I _T					
Ι _Τ	Test Current					
١ _F	Forward Current					
V _F	Forward Voltage @ I _F					

4. 1/2 sine wave (or equivalent square wave), PW = 8.3 ms, duty cycle = 4 pulses per minute maximum.



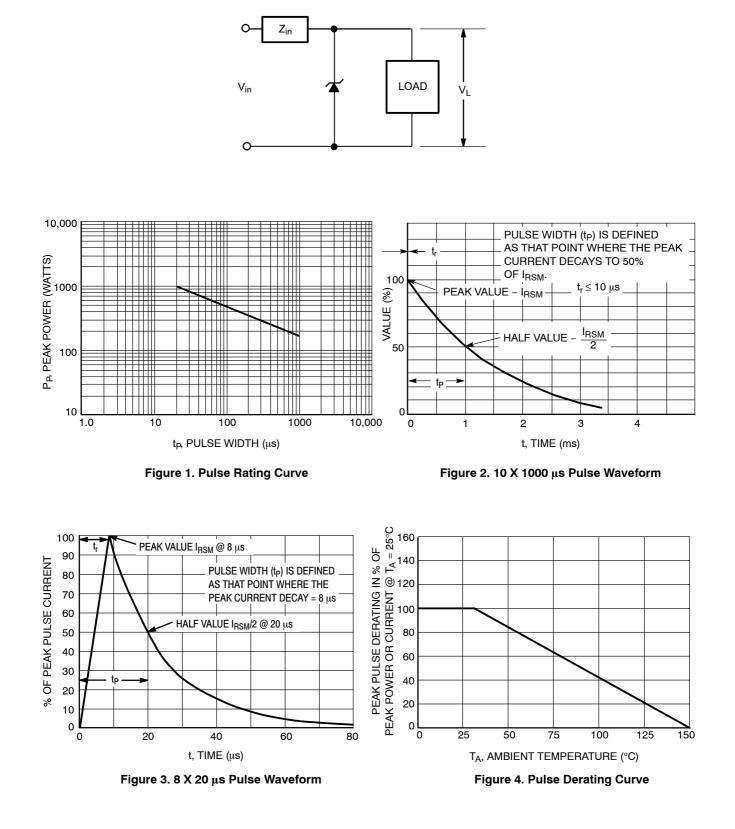
		V _{RWM} (V)	V _{BR} @ I _T (V) (Note 6)			Ι _Τ	$I_R @ V_{RWM}$	V _{C(Max)}	I _{PP(Max)} (A)
Device*	Marking	(Note 5)	Min	Nom	Max	(mA)	(μΑ)	(V)	(Note 7)
SMF5.0AG	KE	5	6.4	6.7	7	10	400	9.2	21.7
SMF6.0AG	KG	6	6.67	7.02	7.37	10	400	10.3	19.4
SMF6.5AG	KK	6.5	7.22	7.6	7.98	10	250	11.2	17.9
SMF7.0AG	KM	7	7.78	8.2	8.6	10	100	12	16.7
SMF7.5AG	KP	7.5	8.33	8.77	9.21	1	50	12.9	15.5
SMF8.0AG	KR	8	8.89	9.36	9.83	1	25	13.6	14.7
SMF9.0AG	KV	9	10	10.55	11.1	1	5	15.4	13.0
SMF10AG	КХ	10	11.1	11.7	12.3	1	2.5	17	11.8
SMF11AG	KZ	11	12.2	12.85	13.5	1	2.5	18.2	11.0
SMF12AG	LE	12	13.3	14	14.7	1	2.5	19.9	10.1
SMF13AG	LG	13	14.4	15.15	15.9	1	1	21.5	9.3
SMF14AG	LK	14	15.6	16.4	17.2	1	1	23.2	8.6
SMF15AG	LM	15	16.7	17.6	18.5	1	1	24.4	8.2
SMF18AG	LT	18	20	21	22.1	1	1	29.2	6.8
SMF20AG	LV	20	22.2	23.35	24.5	1	1	32.4	6.2
SMF22AG	LX	22	24.4	25.6	26.9	1	1	35.5	5.6
SMF24AG	LZ	24	26.7	28.1	29.5	1	1	38.9	5.1
SMF26AG	ME	26	28.9	30.4	31.9	1	1	42.1	4.8
SMF28AG	MG	28	31.1	32.8	34.4	1	1	45.4	4.4
SMF30AG	MK	30	33.3	35.1	36.8	1	1	48.4	4.1
SMF33AG	MM	33	36.7	38.7	40.6	1	1	53.3	3.8
SMF36AG	MP	36	40	42.1	44.2	1	1	58.1	3.4
SMF48AG	MX	48	53.3	56.1	58.9	1	1	77.4	2.6
SMF51AG	MZ	51	56.7	59.7	62.7	1	1	82.4	2.4
SMF58AG	NG	58	64.4	67.8	71.2	1	1	93.6	2.1

ELECTRICAL CHARACTERISTICS ($T_L = 30^{\circ}C$ unless otherwise noted, $V_F = 1.25$ Volts @ 200 mA)

5. A transient suppressor is normally selected according to the Working Peak Reverse Voltage (V_{RWM}) which should be equal to or greater than the DC or continuous peak operating voltage level.
6. V_{BR} measured at pulse test current I_T at ambient temperature of 25°C.
7. Surge current waveform per Figure 2 and derate per Figure 3.

*Include SZ-prefix devices where applicable.

TYPICAL PROTECTION CIRCUIT



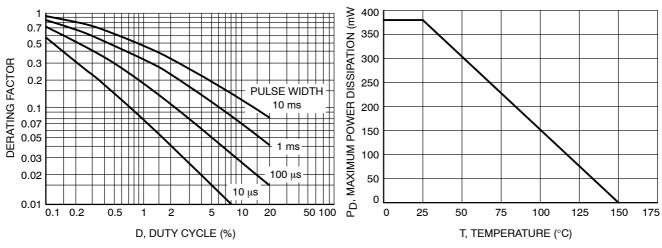
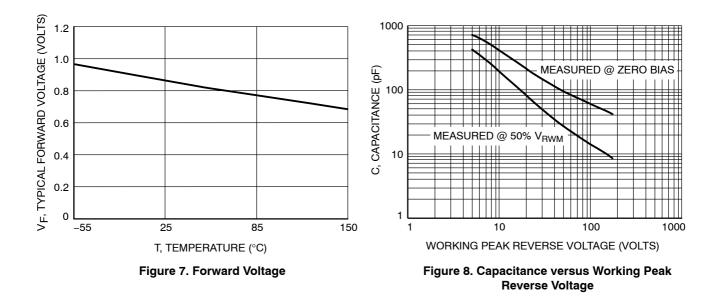


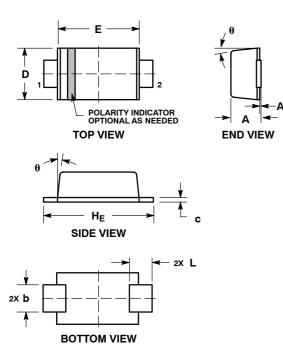
Figure 5. Typical Derating Factor for Duty Cycle

Figure 6. Steady State Power Derating



PACKAGE DIMENSIONS

SOD-123FL CASE 498 ISSUE D



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

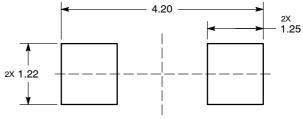
2. CONTROLLING DIMENSION: MILLIMETER.

3. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH.

 DIMENSIONS D AND J ARE TO BE MEASURED ON FLAT SECTION OF THE LEAD: BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.

	м	ILLIMETE	RS	INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.90	0.95	0.98	0.035	0.037	0.039	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
b	0.70	0.90	1.10	0.028	0.035	0.043	
с	0.10	0.15	0.20	0.004	0.006	0.008	
D	1.50	1.65	1.80	0.059	0.065	0.071	
Е	2.50	2.70	2.90	0.098	0.106	0.114	
L	0.55	0.75	0.95	0.022	0.030	0.037	
HE	3.40	3.60	3.80	0.134	0.142	0.150	
θ	0°	-	8°	0°	-	8°	

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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